

FOR IMMEDIATE RELEASE

Contact:

Jenny Ng
SMTA
Tel: (952)-920-7682
Email: jenny@smta.org
Website: www.ipc.org or www.smta.org

Industry-leading associations IPC and SMTA jointly announce the High-Reliability Cleaning and Conformal Coating Conference, scheduled to take place November 13-15, 2018 at Chicago Marriott, Schaumburg, Illinois. The conference is focused on the cleanliness of highly dense electronic assemblies to achieve quality and reliability within the stated in-field environment.

Session 2 of the Technical Conference focuses on “Conformal Coating Highly Dense Electronics.”

Devyn DeVantier of Northrop Grumman Corporation will discuss “Adapting Coating Applications for High-Density Electronics.”

David Hillman of Rockwell Collins will discuss the “Round Robin Testing for IPC Conformal Coating Material & Application Assessment – Interim Report.”

Nico Coenen of Global BDM Electronics Market will discuss “Open Air Plasma Treatment before Conformal Coating.”

Rakesh Kumar, Ph.D. of Specialty Coating Systems will discuss “Increasing Protection and Reliability of High Dense Electronics through Paraylenes.

Come learn about these valuable lessons and more at the IPC/SMTA Cleaning and Conformal Coating Conference.

The link <http://events.ipc.org/events/ipc-and-smta-high-reliability-cleaning-conformal-coating-conference/event-summary-3940b66bd507411cbf7136cb9644c84b.aspx> provides a detail agenda outline.